

Solder Paste	→	Dice Assembled	→	Soldering	→	IPA Cleaning	→	Epoxy Molding
			IPQC		IPQC		IPQC	↓
TMTT Testing	←	Lead Tin Plating	←	Trim Form	←	De-flash	←	After Curing
	↓	OQC		OQC				
Labeling Packing	→	Appearance Checking	→	Stock	→	Outgoing Inspection		



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